



SUSS MICROTEC INVESTOR PRESENTATION

August 2015

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

TABLE OF CONTENT



I. SUSS MicroTec at a Glance

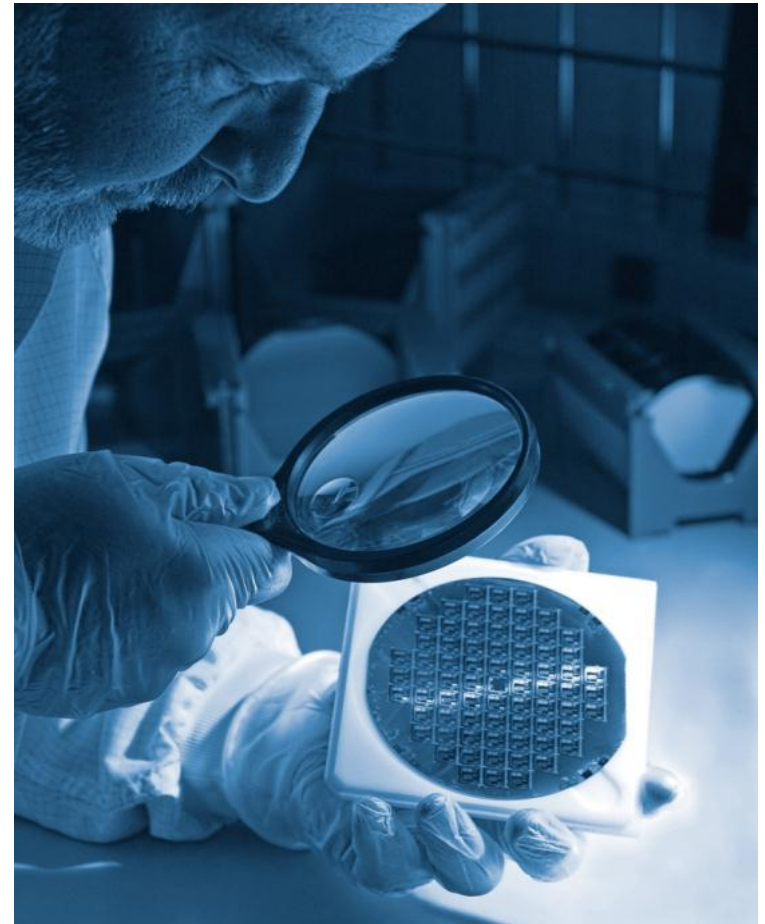
II. Products and Markets

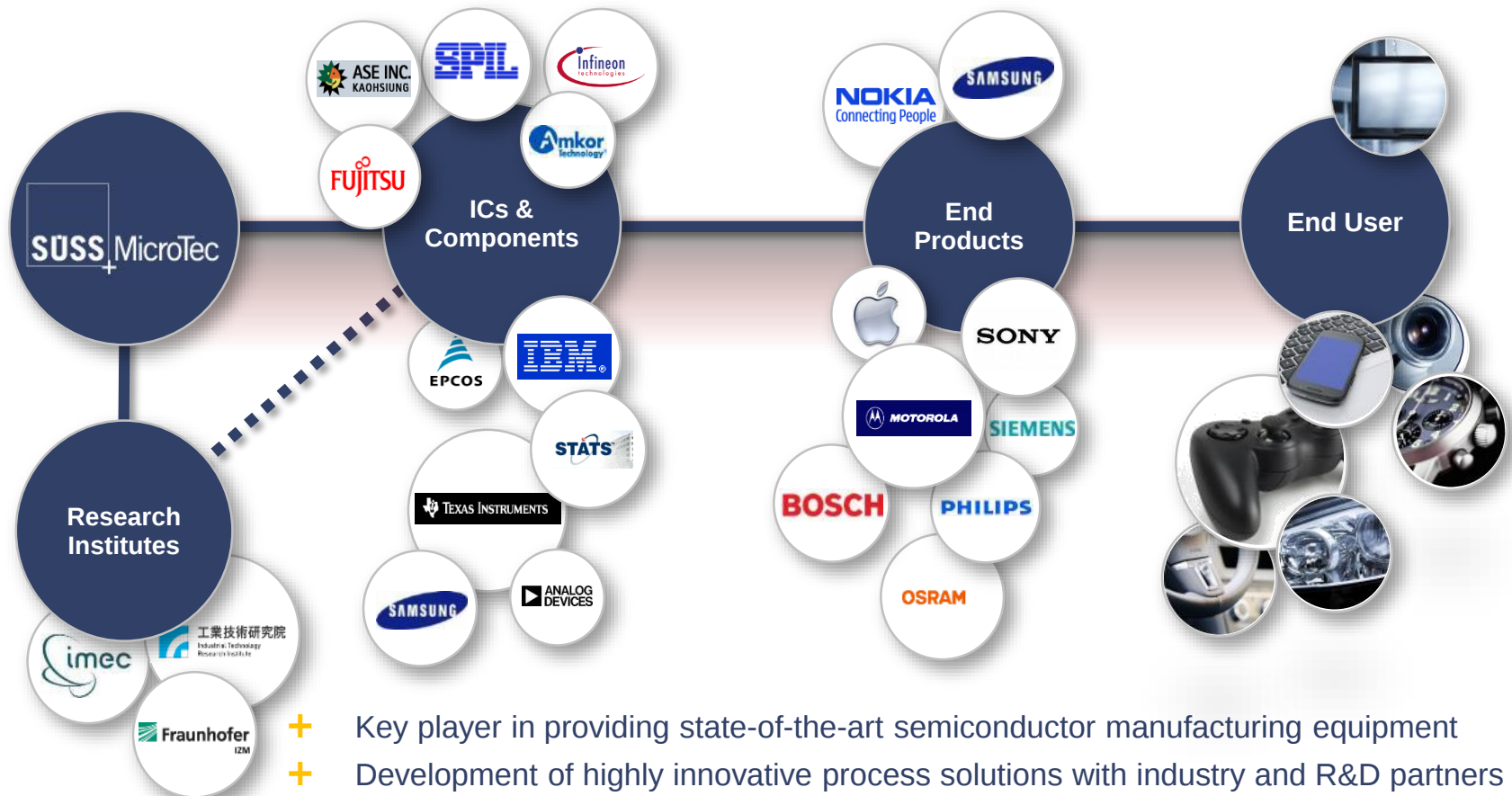
III. Growth Opportunities

IV. Financials

V. Outlook

- + A global leader in manufacturing equipment for the semiconductor mid- and backend market
 - + Our equipment and process solutions create the micro structures that build and connect micro electronic devices
 - + Focus on attractive growth markets: Semiconductors, MEMS and LED
 - + Leading market position in target markets
-
- + Key figures 2014:
 - Order Entry € 134.3 million
 - Sales € 145.3 million
 - Employees: 659





- + Key player in providing state-of-the-art semiconductor manufacturing equipment
- + Development of highly innovative process solutions with industry and R&D partners
- + Key components for electronic devices like cell phones, PCs and tablet computers are produced on SUSS MicroTec's equipment

SUSS MICROTEC – A GLOBAL PLAYER

NORTH AMERICA

Order Entry 18.9 € million
Sales 21.5 € million
Employees 118

EUROPE

Order Entry 41.9 € million
Sales 42.7 € million
Employees 419

ASIA

Order Entry 67.6 € million
Sales 81.1 € million
Employees 122



*Figures refer to the fiscal year 2014

MAIN PRODUCTION SITES

Germany

Sternenfels*

- + Development/production:
 - **Bonder**
 - **Coater and Developer**
 - **Photomask Equipment**
- + Core competencies:
 - **Wet processing**
 - **Wafer bonding**
 - **Photomask Equipment**
- + Production facility ~15,000 m²



Garching*

- + SUSS MicroTec HQ
- + Development/production:
 - **Mask Aligner**
 - **Bond Aligner**
- + Core competencies:
 - **Exposure** (proximity exposure)
 - **Alignment**
 - **Bond Aligner**
- + Production facility ~9,000 m²



USA

Corona (California)

- + Development/production:
 - **Stepper/Scanner**
 - **Laser Processing**
- + Core competencies:
 - **Exposure** (UV projection)
 - **Laser Ablation**



*Production site is owned by SUSS MicroTec

TABLE OF CONTENT



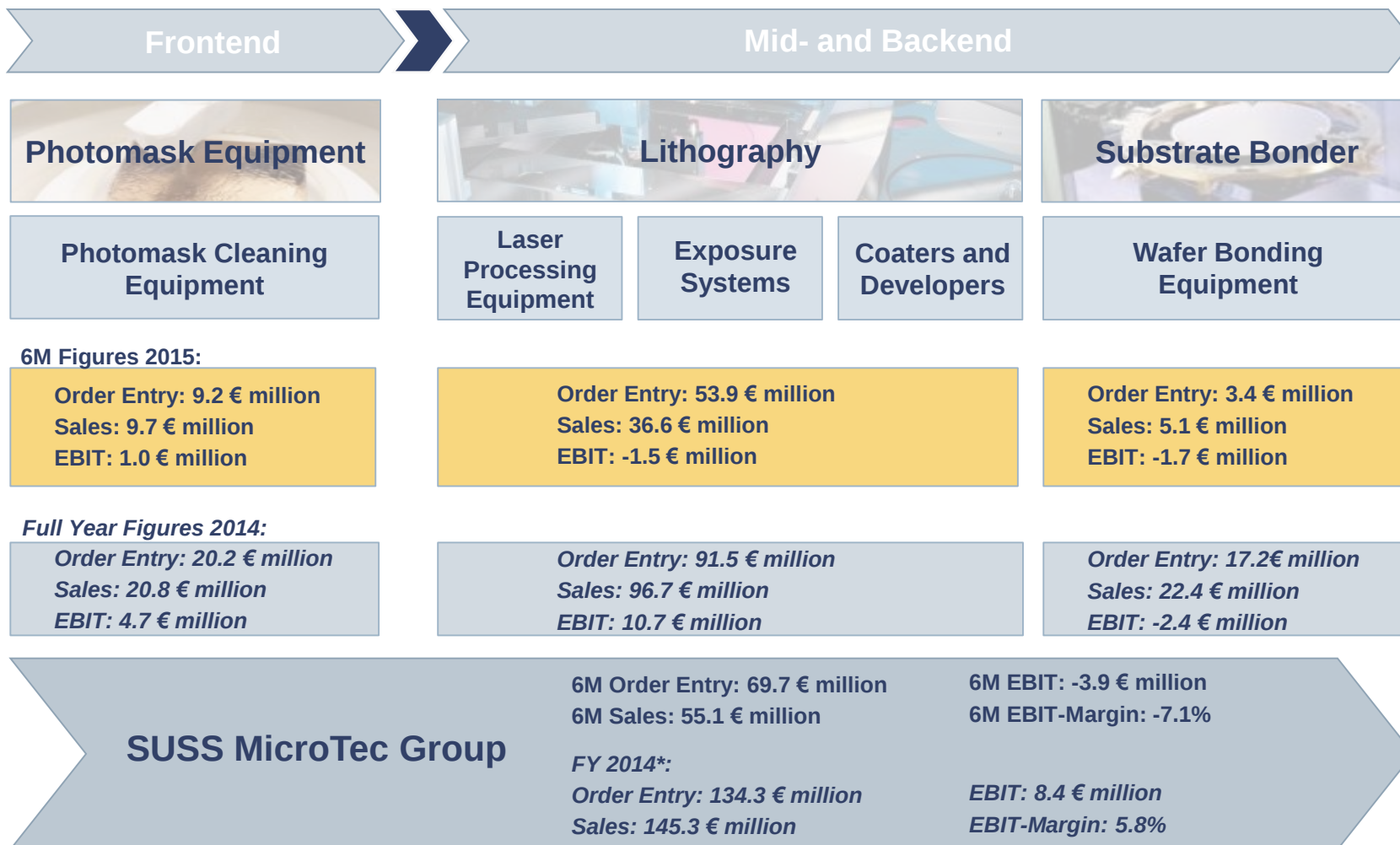
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II. Products and Markets

III. Growth Opportunities

IV. Financials

V. Outlook

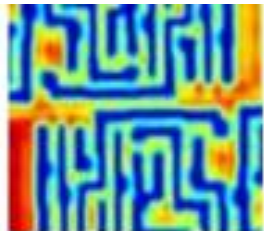


* FY 2014, EBIT Segment Others: -4.5 € million
 H1 2015, EBIT Segment Others: -1.7 € million

Semiconductors

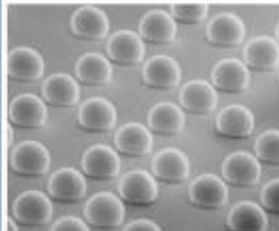
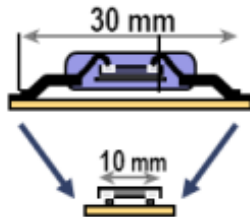
Mask Making

Photomask
Cleaning



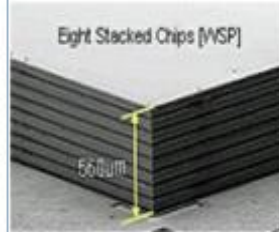
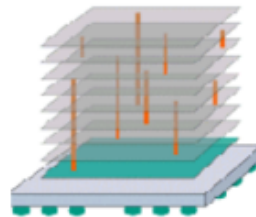
Advanced Packaging

Micro-Bumping



3D Integration

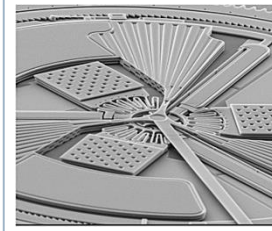
3D (TSV)
Stacking



Sensors

MEMS

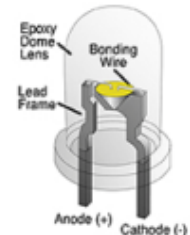
Computing,
Automotive...



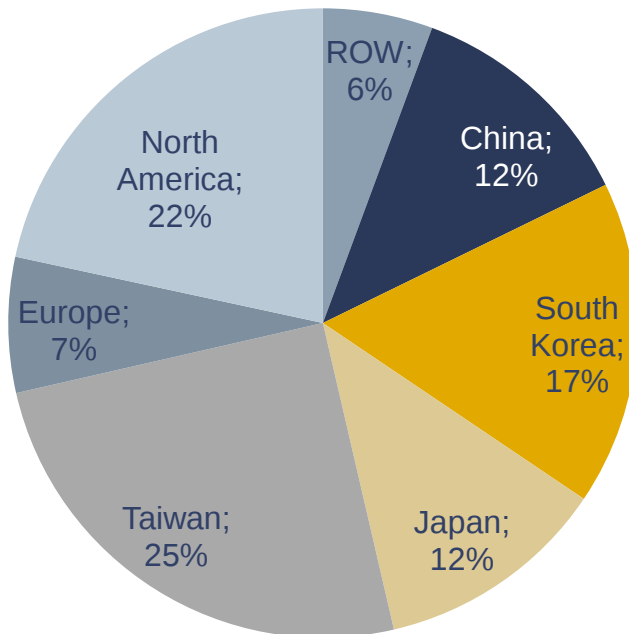
Lighting

LED

General Lighting,
HB and UHB

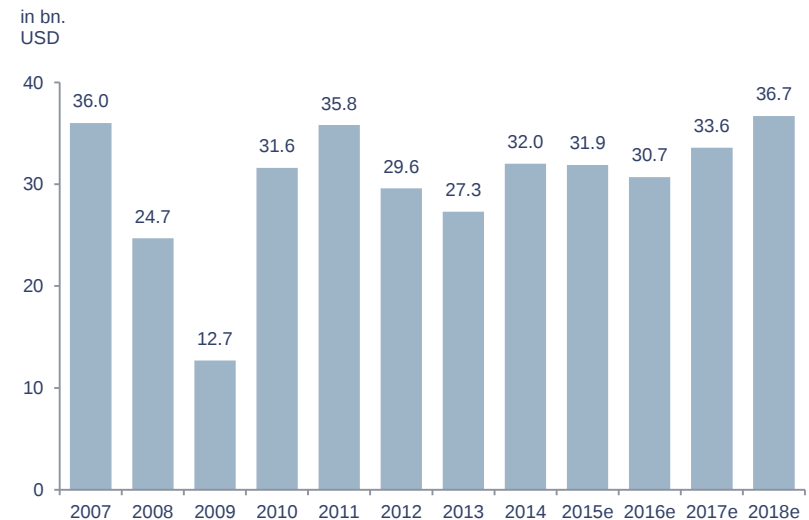


Semiconductor Equipment Sales by Region in 2014



Source: SEMI

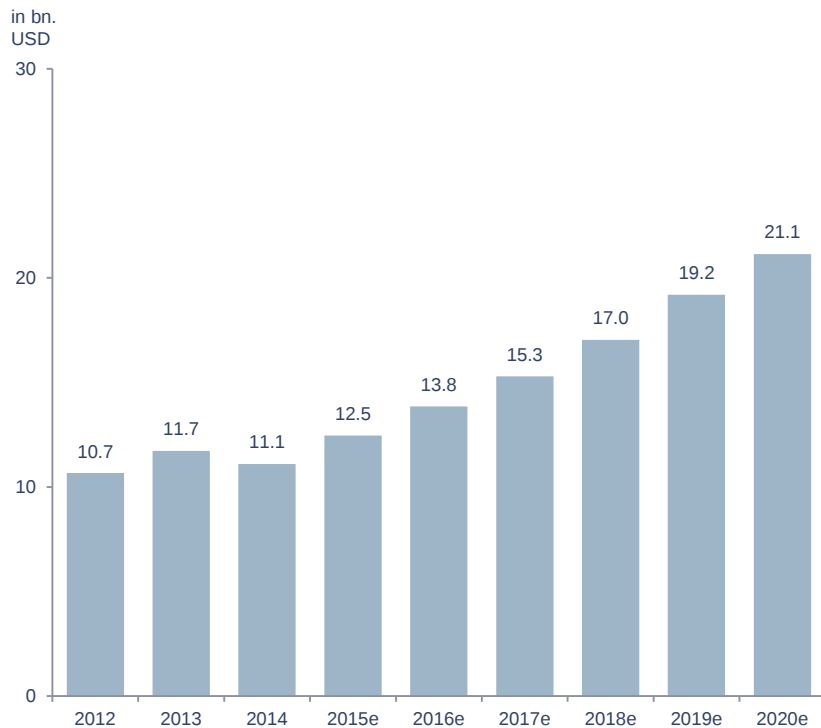
Wafer-Fab Equipment Sales



Source: Gartner, July 2015

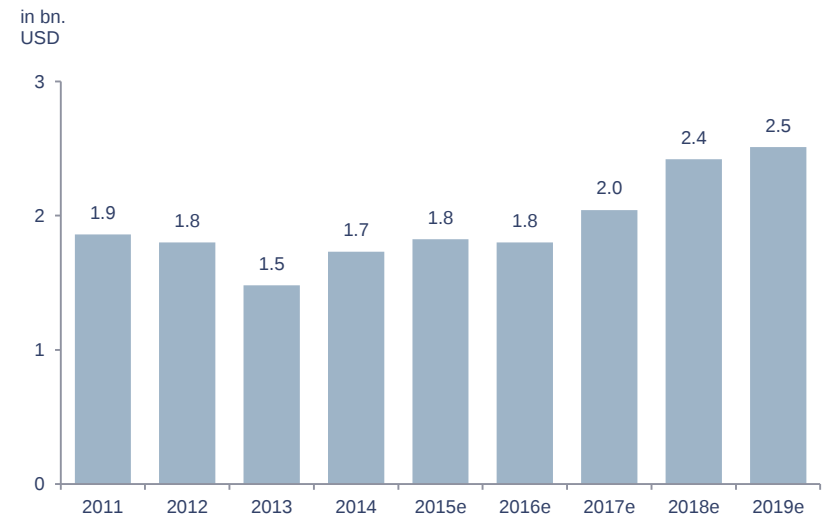
EXPECTED DEVELOPMENT IN KEY MARKETS

MEMS Market



Source: Yole, May 2015

Wafer-Level Packaging and Assembly Equipment



Source: Gartner, July 2015

TABLE OF CONTENT



I. SUSS MicroTec at a Glance

II. Products and Markets

III. Growth Opportunities

IV. Financials

V. Outlook

Digital Lifestyle

- + The „Digital Lifestyle“ is characterized by permanent internet connectivity and convergence of media
- + Mobile devices like smartphones and tablet PCs provide this capability at affordable cost
- + New device generations offer higher functionality



E-Mobility

- + Alternative transportation / mobility solutions are getting more traction with attractive price / performance ratios
- + EVs, Hybrid-Cars, Segways, E-Bikes, but also trains drive the need for power devices and high performance Ics at the same time



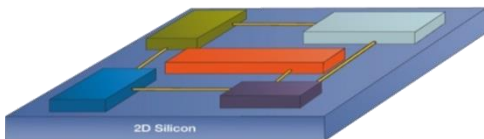
Energy Efficiency

- + Increased environmental awareness and rising energy cost drive the demand for energy efficient solutions i.e. solid state lighting
- + Energy efficiency in industrial production
- + Smart energy management in household applications



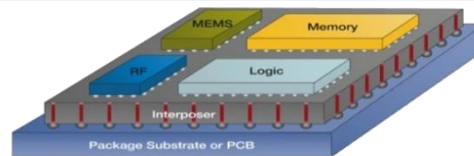
2D Packaging

- Increased performance and complexity of ICs by shrinking transistor geometry according to Moore's Law
- New technologies like EUV and multiple patterning allow further scaling
- Technical challenges and limitations make it increasingly more difficult and expensive to reduce the feature size



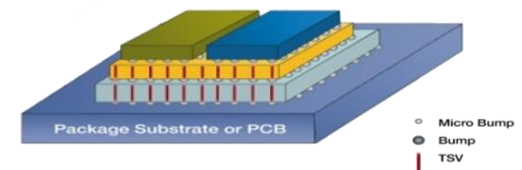
2.5D Packaging

- Combining of several (and heterogeneous) semiconductor components on an interposer addresses limitations of traditional shrinking
- Increased packaging density
- Reduced footprint
- Complementary technology to Moore's Law



3D Integration (TSV)

- The extension beyond the conventional shrink roadmap is called "More than Moore"
- Packaging becomes key enabler for scaling and some manufacturing value is shifting from silicon to the package
- Performance and complexity increase combined with smaller footprint
- Reduced energy consumption



SUSS MicroTec's equipment and process solutions enable 2D shrinking ("*Moore's Law*") and 3D stacking ("*More than Moore*")

TABLE OF CONTENT



I. SUSS MicroTec at a Glance

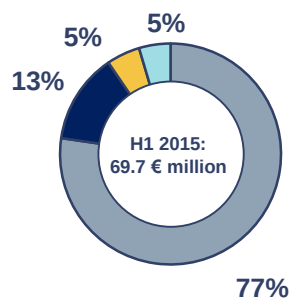
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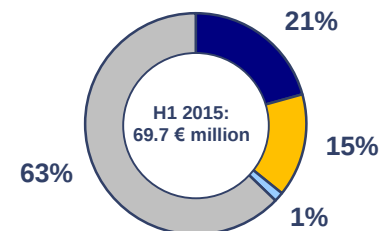
IV. Financials

V. Outlook

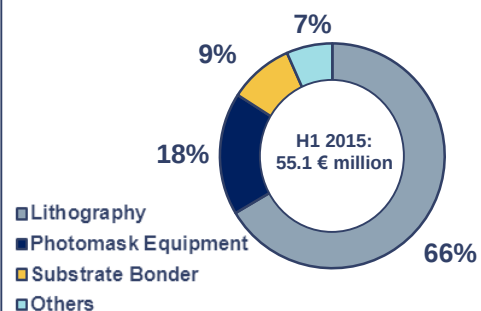
Order Entry by Segment



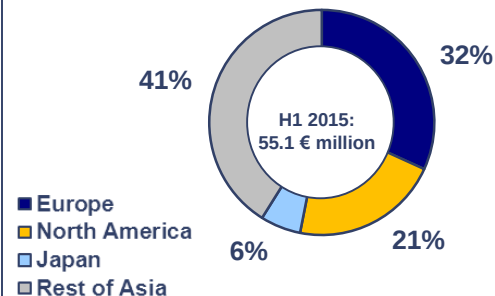
Order Entry by Region



Sales by Segment

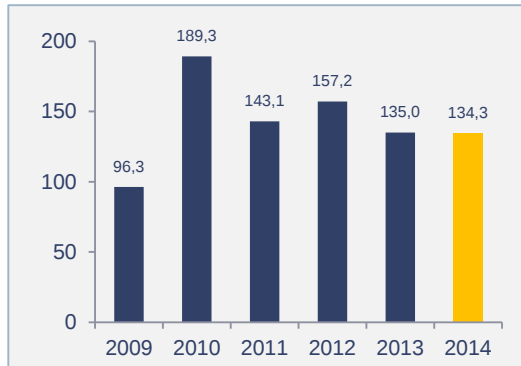


Sales by Region

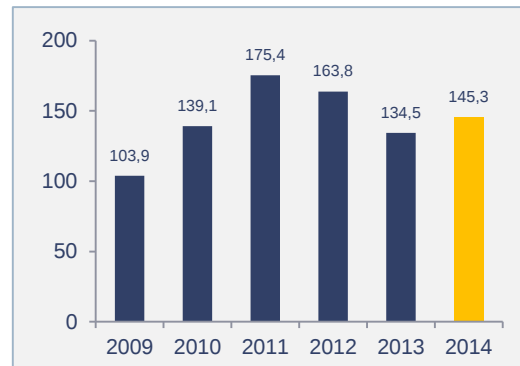


LONG TERM BUSINESS DEVELOPMENT – P&L KEY FIGURES

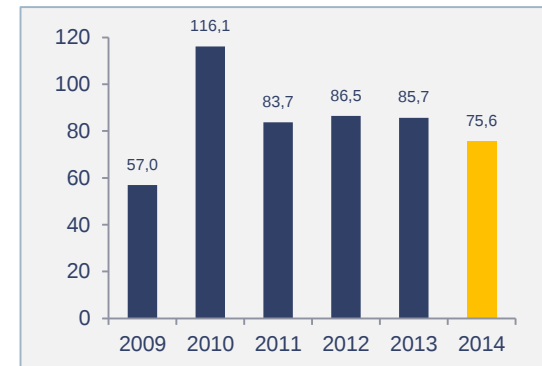
Order Entry in € million



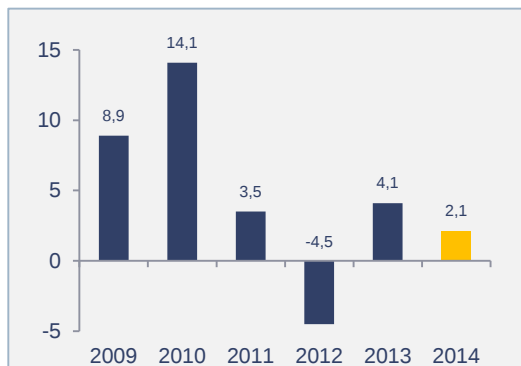
Sales in € million



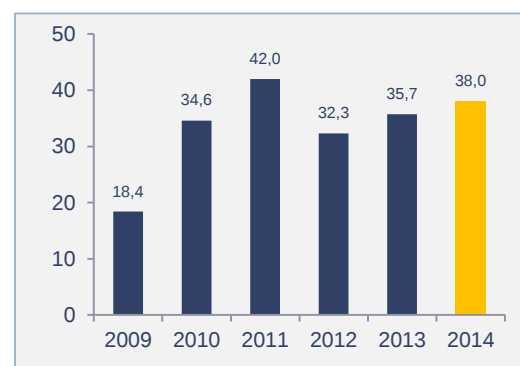
Order backlog in € million



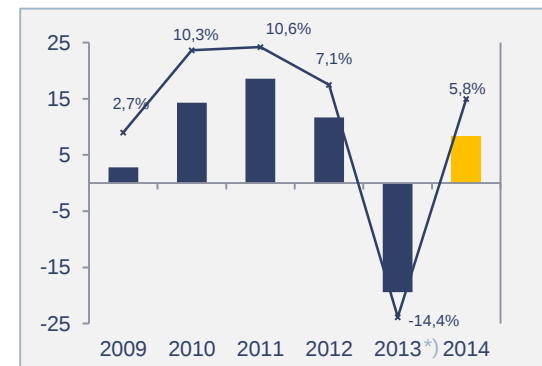
Free Cash Flow in € million



Net cash in € million



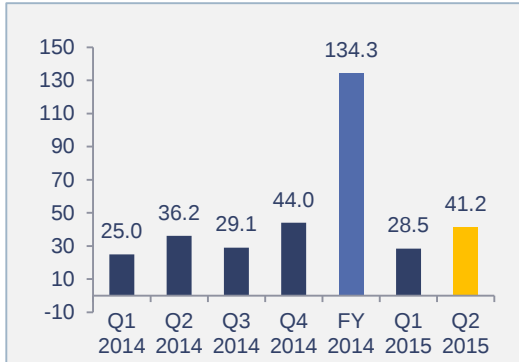
EBIT in € million



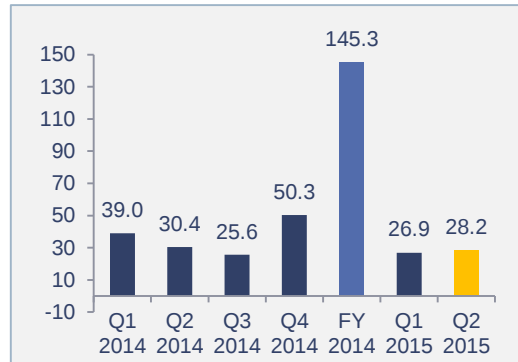
* Including a -13.2 € million one-off effect from restructuring of the product line permanent bonding (-0,69 € per share)

2014 / 2015 - P&L KEY FIGURES BY QUARTER

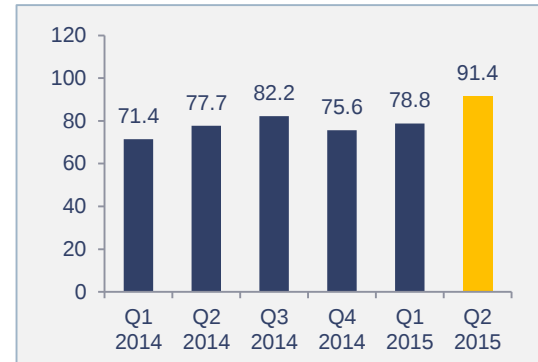
Order Entry in € million



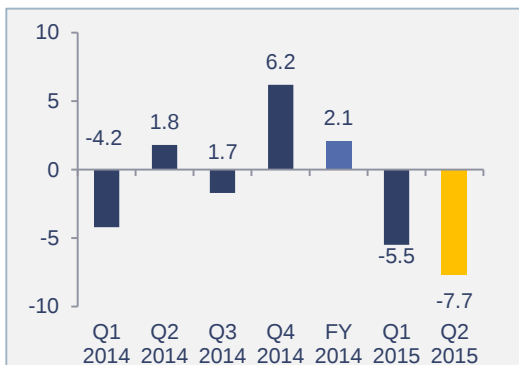
Sales in € million



Order backlog in € million



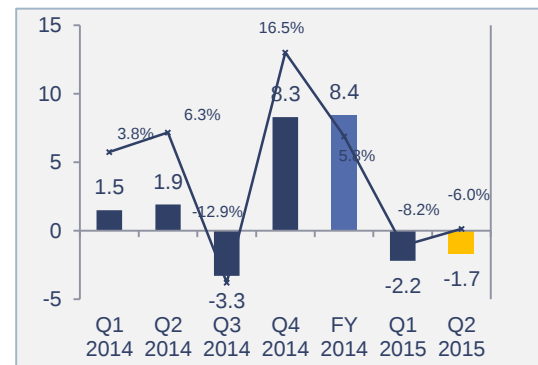
Free Cash Flow in € million



Net cash in € million



EBIT in € million



KEY FINANCIALS

in € million	Q2 2015	Q2 2014	in %
Order Intake	41.2	36.2	13.8%
Order Backlog 6/30	--	--	--
Revenue	28.2	30.4	-7.2%
EBIT	-1.7	1.9	--
<i>EBIT in % of Sales</i>	<i>-6.0%</i>	<i>6.3%</i>	<i>--</i>
Earnings after tax	-2.1	0.9	--
EPS in €	-0.11	0.05	--
Free Cash Flow*	-7.7	1.8	--
Net Cash**	--	--	--
Employees 6/30	--	--	--

<i>H1 2015</i>	<i>H1 2014</i>
69.7	61.2
91.4	77.7
55.1	69.4
-3.9	3.4
<i>-7.1%</i>	<i>4.9%</i>
-4.6	2.0
-0.24	0.11
-13.2	-2.4
25.6	33.3
683	649

* incl. stock of interest-bearing securities

**before consideration of purchased interest-bearing securities

TABLE OF CONTENT



I. SUSS MicroTec at a Glance

II. Products and Markets

III. Growth Opportunities

IV. Financials

V. Outlook

Business Environment/Targets

- + Enabling „Moore’s Law“ and „More than Moore“
- + Fundamental growth in target markets
- + Leveraging the existing technologies and core competencies into products
- + Grow revenue in the Lithography segment and bring the core business back to its former strength
- + Position SUSS MicroTec Photonic systems tools in the market and grow revenue
- + Generate a positive EBIT in the Substrate Bonder Division

Balance Sheet and P&L

- + (Maintain) tight cost structure
- + Strong financial position and positive free cash flow
- + Equity ratio > 60%
- + Target gross margins:
short-term 33 – 35%
medium-term >35%
- + Medium-term EBIT-margin of 5%+

Guidance

FY 2015: Sales: 135 - 145 € million
EBIT: slightly positive

Q3 2015: Order Intake: 25 - 35 € million

Q4 2015: Order Intake: 30 - 40 € million



Thank you!

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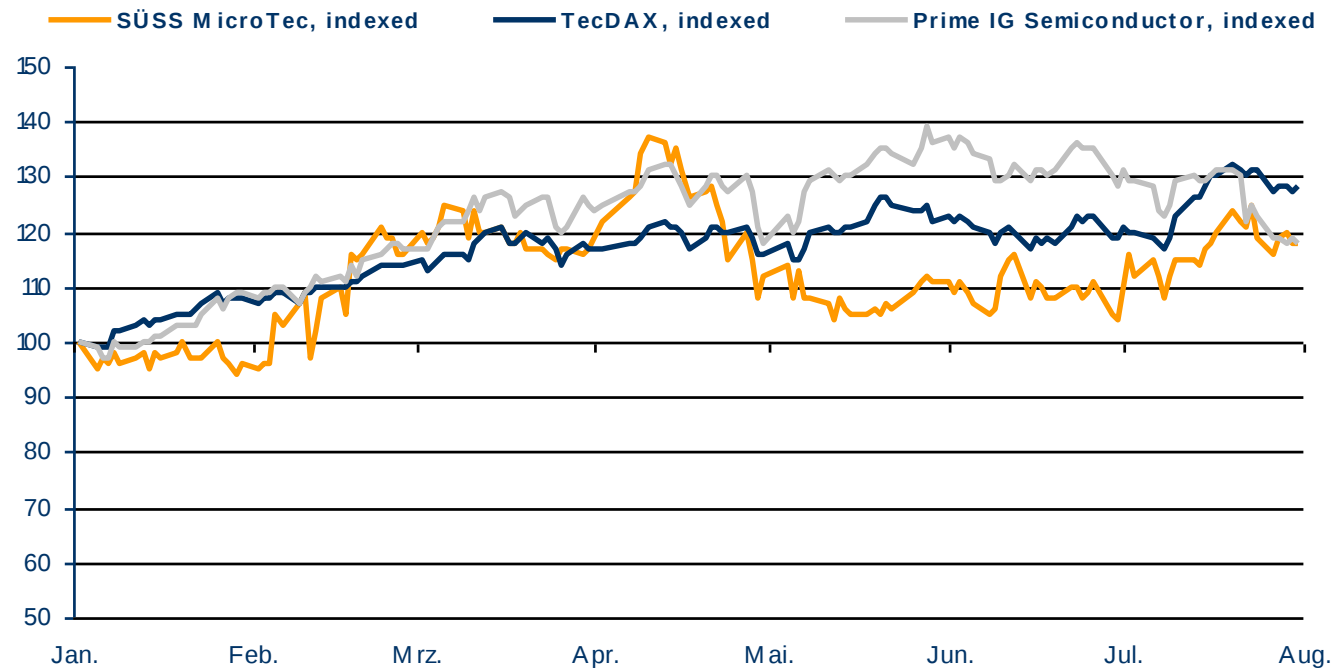
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Financial Calendar 2015

Interim Report 2015	6 Aug
Investment Conference Bankhaus Lampe, Zurich	27 Aug
TMT Conference Commerzbank, Frankfurt	9 Sep
German Corporate Conference, Berenberg/Goldman Sachs, Munich	23 Sep
Nine-month Report 2015	5 Nov
German Equity Forum 2015, Frankfurt am Main	23 - 25 Nov

SHARE PRICE DEVELOPMENT AND MAJOR HOLDERS

(Price of the SÜSS MicroTec Share at January 2, 2015: 4.88 €)

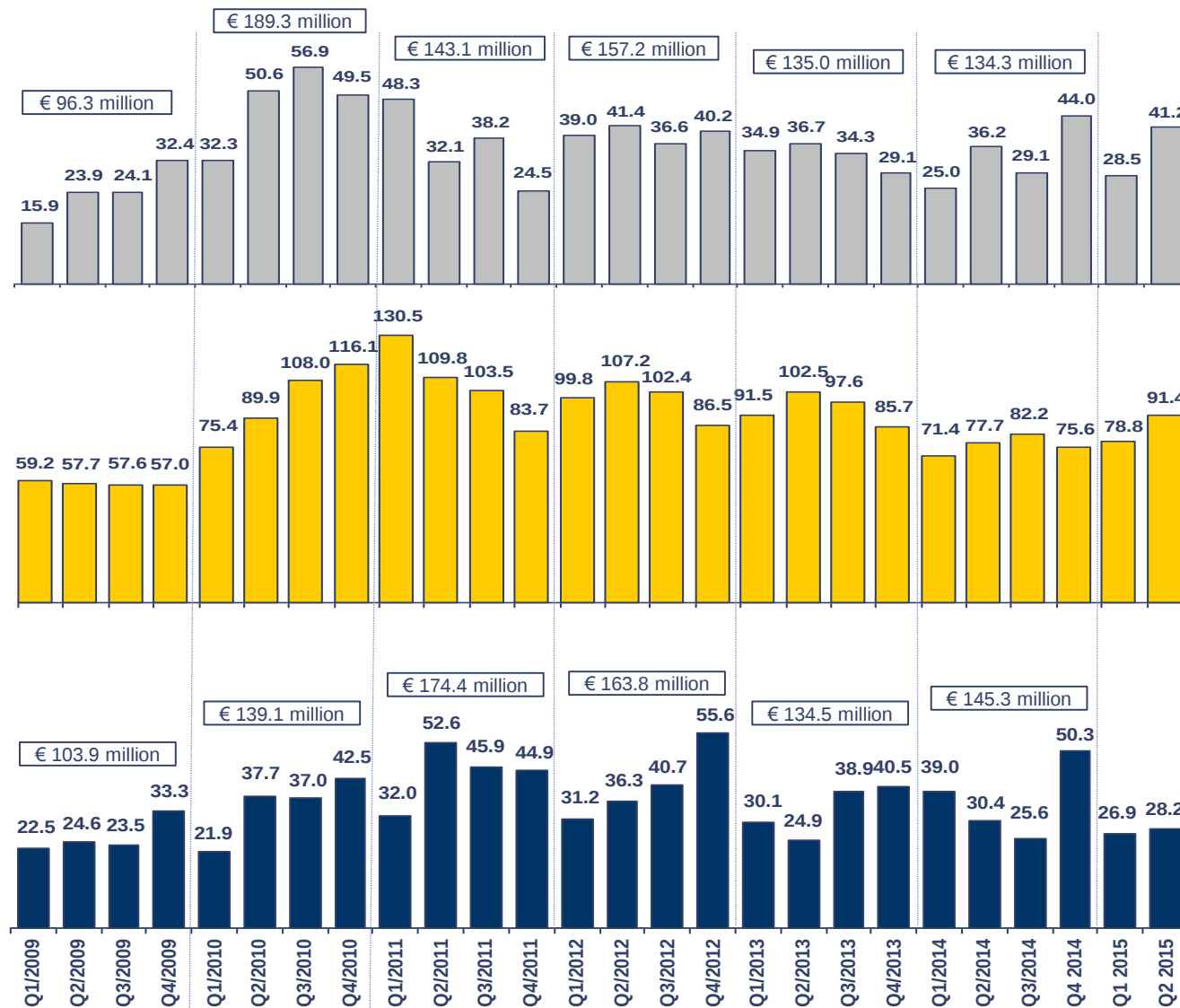


Major Shareholders:

Henderson	5.1%
Universal	5.0%
Sycomore	3.1%
INKA	3.1%
Baillie Gifford	3.0%

Average daily trading volume January – July 2015: ~ 144,000

LONG TERM BUSINESS DEVELOPMENT BY QUARTER



EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT

